Amendments to the Specification:

Please replace the paragraph beginning at page 5, line 3, with the following amended paragraph:

Copper alloy leadframes are normally plated with silver (Ag) or an alloy in order to facilitate the bonding of wires to the leadframe. Alloys that can be used as alternative plating materials include Ni/Au, Ni/Pd, Ni/Pd/Au, and Ni/Pd/Au alloys. The plating covers the areas of the lead fingers or die-attach pad where electrical connections are to be made to other components, typically by wire bonding. **Figs. 3A-3H** are top views of a dual side package 20 having a die-attach pad 22 and lead fingers (or metal contacts if the package is unleaded) 24A-24H, with the semiconductor die omitted to show several patterns in which the plating can be performed. In each drawing, the hatched ~~plated~~ areas are plated ~~hatched~~; the clear areas are roughened in accordance with this invention. **Fig. 3A** ~~In **Fig. 3A**,~~ shows a "normal" configuration, wherein substantially all of die-attach pad 22 and the bonding areas of lead fingers 24A-24H are plated. In **Fig. 3B**, die-attach pad 22 is unplated and lead fingers 24A-24H are "spot" plated. In **Fig. 3C**, both die-attach pad 22 and lead fingers 24A-24H are "spot" plated. In **Fig. 3D**, a ring is plated at the perimeter of die-attach pad 22 and substantially all of the bonding areas of lead fingers 24 are plated. In **Fig. 3E**, a ring is plated just inside the perimeter of die-attach pad 22 and lead fingers 24A-24H are "spot" plated. In **Fig. 3F**, a double-ring is plated on die-attach pad 22 and lead fingers 24A-24H are "spot" plated. In **Fig. 3G**, specific areas of die-attach pad 22 are plated and lead fingers 24A-24H are "spot" plated. In **Fig. 3H**, die-attach pad 22 is plated with a ring and specific areas, and lead fingers 24A-24H are "spot" plated.

SILICON VALLEY
'ATENT GROUP LLP

50 Mission College Blvd
Suite 360
Santa Clara, CA 95054
(408) 982-8200
FAX (408) 982-8210